

# SPECIFICATION

CUSTOMER: \_\_\_\_\_  
PRODUCT : 声表谐振器  
MODEL NO: LT-SR-315-D11  
PREPARED: 杨嘉妮 CHECKED: 顾杰  
D A T E: 2022-03-10

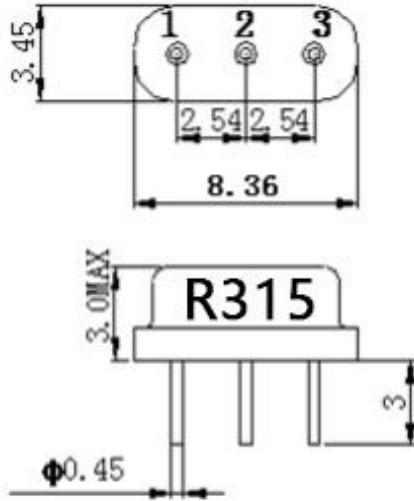
CUSTOMER RECEIVED:		
CHECKED	APPROVED	DATE

## 版本说明

日期	版本号	修订说明	拟制	审核
2022-03-10	1.0	初版	杨嘉妮	顾杰

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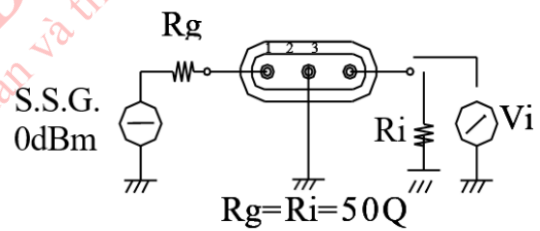
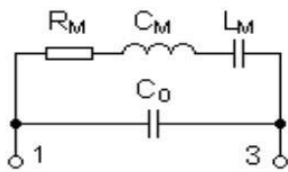
1. Package Dimension (D -11)



Pin	Connection
1	Input/ Output
2	Case Ground
3	Output/ Input

Marking	
R	SAW resonator
R315	Center Frequency

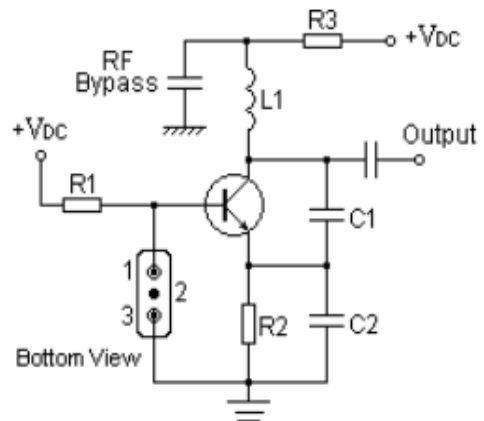
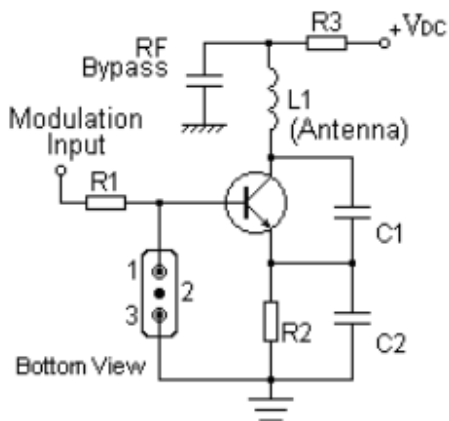
2. Equivalent LC Model and Test Circuit



3. Typical Application Circuit

1) Typical Low-Power Transmitter Application

2) Typical Local Oscillator Application



#### 4. Typical Frequency Response



#### 5. Performance

##### 5-1. Maximum Rating

Rating	Value	Units
CW RF Power Dissipation	+10	dBm
DC Voltage Between Any Two Pins	$\pm 30V$	V
Operation Temperature	-40 to +85	$^{\circ}C$
Storage Temperature	-55 to +125	$^{\circ}C$

##### 5-2. Electronic Characteristics

Characteristic		Sym	Minimum	Typical	Maximum	Units
Center Frequency (+25 $^{\circ}C$ )	Absolute Frequency	$f_c$		315.000		MHz
	Tolerance from 315.000MHz	$\Delta f_c$		$\pm 75$		kHz
Insertion Loss		IL		1.5	2.0	dB
Quality Factor	Unloaded Q	$Q_U$		17396		
	50 $\Omega$ Loaded Q	$Q_L$		2518		
Temperature Stability	Turnover Temperature	$T_o$	25	40	55	$^{\circ}C$
	Frequency Temperature Coefficient	FTC		0.032		ppm/ $^{\circ}C^2$
Frequency Aging Absolute Value during the First Year		$ f_A $		$\leq 10$		ppm/yr
DC Insulation Resistance Between Any Two Pins			1.0			M $\Omega$
RF Equivalent RLC Model	Motional Resistance	$R_M$		16.9	25	$\Omega$
	Motional Inductance	$L_M$		148.8		$\mu H$
	Motional Capacitance	$C_M$		1.72		fF
	Pin 1 to Pin 3 Static Capacitance	$C_O$	2.3	2.6	2.9	pF

**CAUTION: Electrostatic Sensitive Device. Observe precautions for handling!****Notes:**

1. As a result of the particularity of inner structure of SAW products, it easy to be breakdown by electrostatic, so we should pay attention to ESD protect in the test.
2. Static voltage between signal load and ground may cause deterioration and destruction of the component. Please avoid static voltage.
3. Ultrasonic cleaning may cause deterioration and destruction of the component. Please avoid ultrasonic cleaning.
4. Only leads of component may be soldered. Please avoid soldering another part of component.
5. There is a close relationship between the device's performance and matching network. The specifications of this device are based on the test circuit shown above. L and C values may change depending on board layout. Values shown are intended as a guide only.

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